

# **Product Marking Change**

XCN12021 (v1.1.1) October 10, 2012

Product Change Notice - For Information Only

### Overview

The purpose of this notification is to notify customers of a product marking change for some Xilinx<sup>®</sup> FPGA products.

## **Description**

Xilinx is implementing a new product marking change for Xilinx FPGAs products. This change only affects products metal lid or bare die packages that are laser marked. Automotive "XA" and Aerospace / Defense "XQ" products are not affected.

To support customer demand on a specific speed & temperature grade device, there are instances where Xilinx will retest devices that are pre-marked with a different speed & temperature grade. Prior to this notification, the existing speed & temperature grade mark has been covered and the new speed & temperature grade is then marked on the device. This process is no longer possible with laser marked devices, therefore, Xilinx is changing the speed & temperature grade marking on line #4 (see Traceability example below) for laser marked FPGA devices to allow multiple speed and temperature grades.

#### Note:

- 1. This type of marking will only be used when pre-marked "individual" devices are production tested to meet another speed & temperature grade requirement.
- 2. Each ordered device will only meet the unique specification reflected in the speed & temperature grade top marking. Any devices marked with a single speed & grade temperature mark are not tested to, nor guaranteed to meet multiple speed grade specifications.

There is no change to the form, fit, or function.

### **Products Affected**

This change can affect all speed, package, and temperature variations of Xilinx FPGAs with laser mark.

## Key Dates and Ordering Information

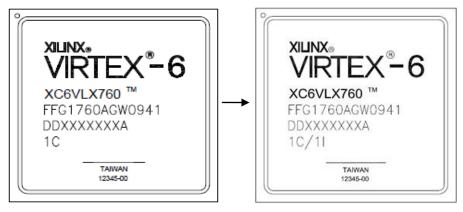
This change is effective upon the release of this notification.

© Copyright 2012 Xilinx, Inc. Xilinx, the Xilinx logo, Artix, ISE, Kintex, Spartan, Virtex, Zynq, and other designated brands included herein are trademarks of Xilinx in the United States and other countries. All other trademarks are the property of their respective owners.



### **Traceability**

Product marking example (Marking content is not real lot information):



Standard Laser Marking

New Re-marking

### Response

No response is required. For additional information or questions, please contact Xilinx Technical Support <a href="http://www.xilinx.com/support/techsup/tappinfo.htm">http://www.xilinx.com/support/techsup/tappinfo.htm</a>.

Important Notice: Xilinx Customer Notifications (XCNs, XDNs, and Quality Alerts) can be delivered via e-mail alerts sent by the Support website (<a href="http://www.xilinx.com/support">http://www.xilinx.com/support</a>). Register today and personalize your "Documentation and Design Advisory Alerts" area to include Customer Notifications. Xilinx Support provides many benefits, including the ability to receive alerts for new and updated information about specific products, as well as alerts for other publications such as data sheets, errata, application notes, etc. For information on how to sign up, refer to Answer Record 18683: <a href="http://www.xilinx.com/support/answers/18683.htm">http://www.xilinx.com/support/answers/18683.htm</a>.

## **Revision History**

The following table shows the revision history for this document.

Date	Version	Revision
10/08/12	1.0	Initial release.
10/09/12	1.1	Replace new "Current Re-marking" image to improve marketing example clarification.
10/10/12	1.1.1	Correct the wording from "Current Re-Marketing" to "Standard Laser Marking".

### Notice of Disclaimer

The information disclosed to you hereunder (the "Materials") is provided solely for the selection and use of Xilinx products. To the maximum extent permitted by applicable law: (1) Materials are made available "AS IS" and with all faults, Xilinx hereby DISCLAIMS ALL WARRANTIES AND CONDITIONS, EXPRESS, IMPLIED, OR STATUTORY, INCLUDING BUT NOT LIMITED TO WARRANTIES OF MERCHANTABILITY, NON-INFRINGEMENT, OR FITNESS FOR ANY PARTICULAR PURPOSE; and (2) Xilinx shall not be liable (whether in contract or tort, including negligence, or under any other theory of liability) for any loss or damage of any kind or nature related to, arising under, or in connection with, the Materials (including your use of the Materials), including for any direct, indirect, special, incidental, or consequential loss or damage (including loss of data, profits, goodwill, or any type of loss or damage suffered as a result of any action brought by a third party) even if such damage or loss was reasonably foreseeable or Xilinx had been advised of the possibility of the same. Xilinx assumes no obligation to correct any errors contained in the Materials, or to advise you of any corrections or update. You may not reproduce, modify, distribute, or publicly display the Materials without prior written consent. Certain products are subject to the terms and conditions of the Limited Warranties which can be viewed at http://www.xilinx.com/warranty.htm; IP cores may be subject to warranty and support terms contained in a license issued to you by Xilinx. Xilinx products are not designed or intended to be fail-safe or for use in any application requiring fail-safe performance; you assume sole risk and liability for use of Xilinx products in Critical Applications: http://www.xilinx.com/warranty.htm#critapps.